

08/54/291



Serial No.:  
Inventor(s): Farnsworth et al.

BONDPAD ATTACHMENTS USED TO TEMPORARILY  
CONNECT SEMICONDUCTOR DIE

ABSTRACT

A die contacting substrate establishes ohmic contact with  
5 the die by means of raised portions on contact members. The  
raised portions are dimensioned so that a compression force  
applied to the die against the substrate results in a limited  
penetration of the contact member into the bondpads. The  
arrangement may be used for establishing electrical contact  
10 and with a burn-in oven and with a discrete die tester. This  
permits the die to be characterized prior to assembly, so that  
the die may then be transferred in an unpackaged form. A  
Z-axis anisotropic conductive interconnect material may be  
interposed between the die attachment surface and the die.